affixing the opposite face of the chip to a stiffening substrate to form an assembly composed of the chip and the stiffening substrate;

forming on a face of a support a communication interface having at least one element for connection with the chip;

.cont B'

presenting the assembly against the communication interface, with the connection pad against a corresponding connection element of the communication interface;

fixing and electrically coupling the connection pad with the corresponding connection element; and

removing the stiffening substrate from the opposite face.

2. (Twice Amended) A method according to Claim 1, wherein the communication interface comprises at least one of an ohmic contact area and antenna area produced on a portion of the face of the support which is coplanar with the general plane of the face of the support.

3. (Twice Amended) A method according to Claim 1, wherein the fixing and electrical coupling of the connection pad to the corresponding connection element includes welding the connection pad to the corresponding connection element by passing a laser beam through the stiffening substrate and the chip, said substrate and chip being transparent to the wavelength of the laser beam used for the welding, wherein at least one of the pad or the connection element is fusible under the effect of said laser beam.

cont B1

4. (Twice Amended) A method according to claim 1, wherein the support is in a roll form.

B2

6. (Twice Amended) A method according to claim 1, further including a step of:

cutting the assembly into a form corresponding substantially to the dimensions of the chip, before the step of presenting the assembly.

7. (Twice Amended) A method according to claim 1 wherein the connection pad is fixed with its corresponding connection element by applying a compression force through the stiffening substrate of the assembly.

8. (Twice Amended) A method according to Claim 6, wherein the fixing and electrically coupling includes welding by means of a laser beam which passes through the stiffening substrate and the chip, said substrate and chip being transparent to the wavelengths of the laser beam used for the welding, wherein at least one of the pad the connection element is fusible under the effect of said laser beam.

9. (Amended) Tooling for implementing the method according to Claim 8, comprising a laser with a wavelength of 1.06 μm, whose beam is transmitted by a plurality of optical paths, each of the optical paths directed towards a respective pad of the chip, in order to effect welds in parallel.

B3

11. (Twice Amended) Tooling according to Claim 9 wherein the optical paths are integrated in a tool for positioning and/or holding the assembly with respect to the support.

12. (Twice Amended) A device with an integrated-circuit chip comprising:

at least one chip with a front face provided with at least one connection pad and an opposite face;

a substrate, said chip being mounted on said substrate;

a support having an interface in an overall plane of one face of the support for communication with the chip including at least one connection element; and

said connection pad being fixed and electrically coupled against a corresponding connection element of said interface.

13. (Twice Amended) A device according to Claim 12, further including a protective film over the face of the support.

14. (Twice Amended) A device according to Claim 12 wherein the thickness of the connection elements, the chip, and the pads together is less than 50 microns.